PRODUCT ADVANTAGE

- Low & High Temperature Curing Options
- Conductive & Insulating Materials
- High Thermal & Electrical Conductivity
- Low Temperature Cure for High Temperature Applications
- High Reliability
- No Delamination

OUR THREE PILLARS

1. EXCEEDING PERFORMANCE SPECIFICATIONS
2. MAXIMIZING PRODUCTIVITY
3. LOWERING PROCESS COST

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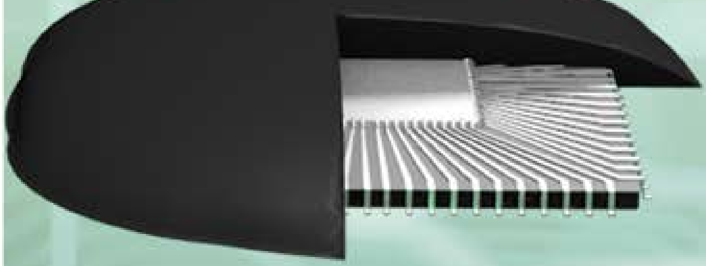
YPB-006 (Version 5/2017)

YINCAE®

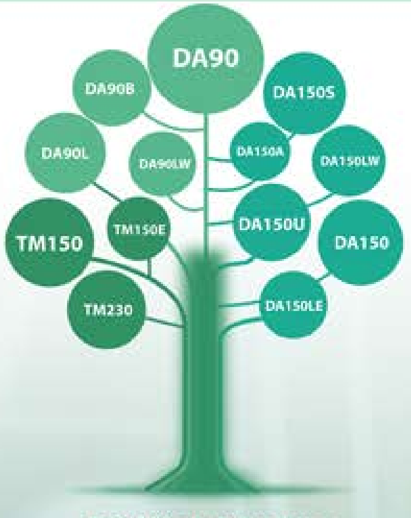
INNOVATION AT ITS BEST



DIE ATTACH MATERIALS OVERVIEW

Preferred by global leaders in the electronics manufacturing industry

YINCAE® Die Attach Adhesives



Die Attach Adhesives

YINCAE® manufactures conductive and insulating materials for die attach applications

DA 90 Series: Low temperature conductive and insulating die attach adhesives (e.g. DA 90, 30 - 60 minute cure at 80 - 110°C)

DA 150 Series: High temperature conductive and insulating die attach adhesives (e.g. DA 150, 6 - 10 minute cure at 150°C)

Benefits

High reliability (15 years at 215°C)
Low stress
Excellent mechanical resistance
High heat dissipation
No delamination

YINCAE® TM solderable conductive adhesive products are rapid cure, self-filling, self-leveling, and self-soldering. They can be used as die attach adhesives for various devices, including LED, CSP, QFP..., to replace conductive adhesives (Ag) or solder materials.

Benefits

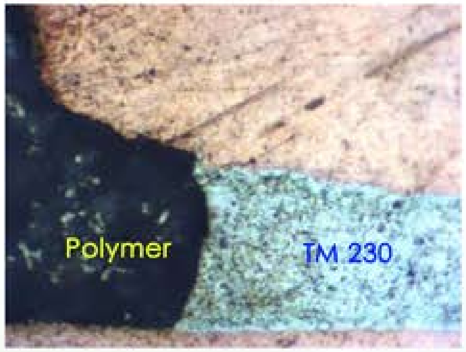
High thermal conductivity
No outgassing, die shifting, or die skewing

Featured Products

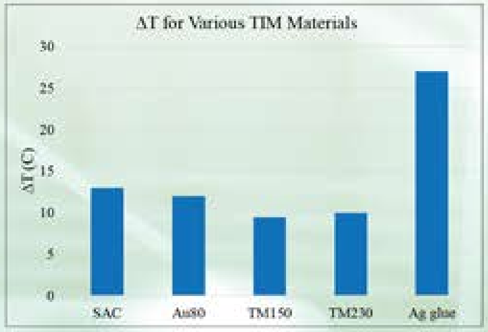
TM 158: diamond filled, high thermal conductivity (60 W/mK), and can withstand very high temperature (400°C) applications

TM 230: ultra-quick, 60 seconds, cure and high thermal conductivity (58 W/mK)

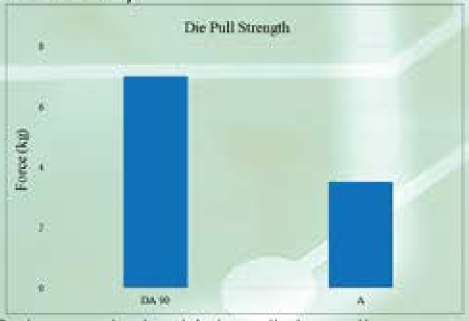
Product	Product Application	Curing Temp. (°C)
DA 90	Silver filled, conductive adhesive	80 – 110
DA 90B	Silver filled, conductive adhesive	80 – 110
DA 90LW	Insulating adhesive for LED chip bonding	80 – 110
DA 90UV	Insulating adhesive for optoelectronic devices	80 – 110
DA 150	Silver filled, conductive adhesive	150
DA 150LE	Insulating adhesive for LED chip bonding	150
DA 150S	Silica filled, insulating adhesive	150
DA 150U	Insulating adhesive for GaN bonding	150
TM 150	Silver filled, solderable conductive adhesive	180
TM 150E	Silver filled, solderable conductive adhesive	150
TM 158	Diamond filled, solderable conductive adhesive	150
TM 230	Silver filled, solderable conductive adhesive	230



Cured TM 230. The adhesive forms a strong bond between the component and substrate while a polymer layer forms during reflow to protect against harsh environmental conditions.



YINCAE® TM series products show the lowest change in temperature suggesting they have the highest thermal conductivity.



DA 90 demonstrates high pull strength.

Gold to PCB substrate, A is a commerically available die attach adhesive

Contact YINCAE at info@yincae.com for detailed specifications & customization for your specific product requirements.